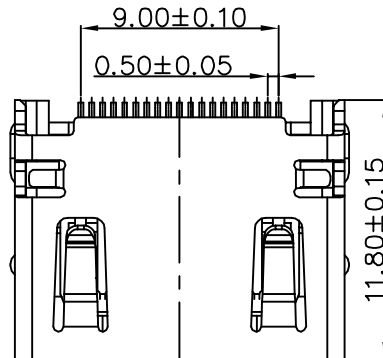
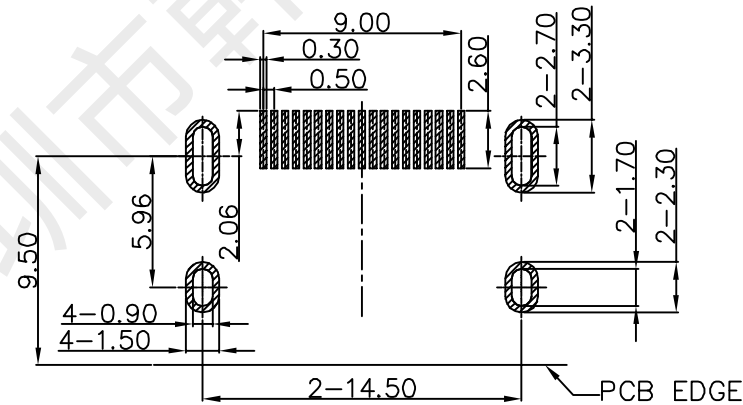
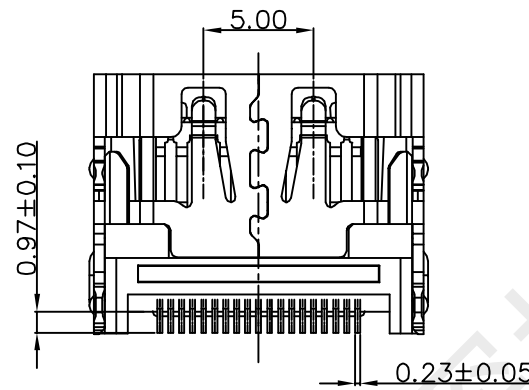
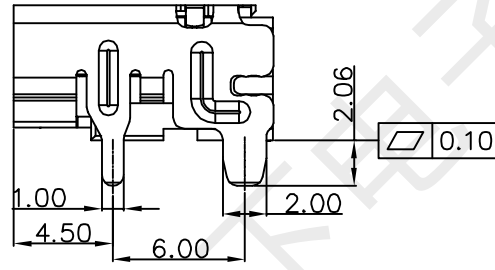
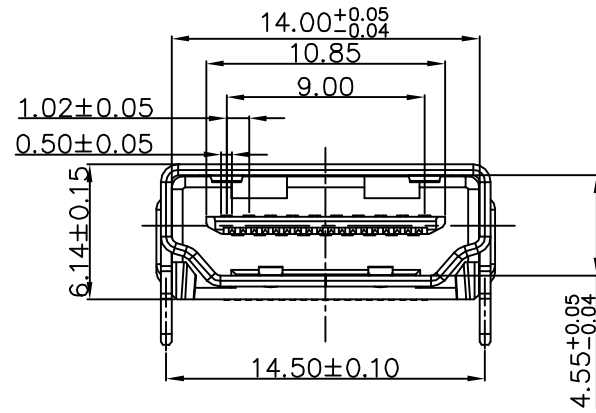


后视图



RECOMMEND PCB LAYOUT (T=1.00)
PCB TOLERANCE: ±0.05

1.Material:

InsertMolding:LCP UL 94V-0 Black
Contact:Copper alloy,T=0.20mm
Shell:SPCC,T=0.50mm

2.Electrical

- 1.1.Rated Voltage:40V AC/DC maximum
- 1.2.Rated Current:0.3A max.
- 1.3.Dielectric strength:150V AC/1 minute
- 1.4.Insulation Resistance:150V DC 10MΩ min.
- 1.5.Contact Resistance:30mΩ Max.

3.Mechanical

- 2.1.Insertion Force Max:4.0kgf max.
- 2.2.Removal Force Min:1.0kgf min. , 4.0kgf max.
- 2.3.Durability: 10000 cycles at 100±50 cycles per hour

4.Plating

- 4.1.Terminal:Contact area:1u" gold plate over 50u" Ni min.
Solder area:100u" pure TIN plate over 50u" Ni min.
- 4.2.Shell: Ni:100u"min.

5.Ambient Temperature: -20°C~+85°C.

REV	DESCRIPTION	DATE
B		
A		

X. ± 0.30	APPD: 罗孝金	深圳市韩下电子有限公司	
.X ± 0.25	CHKD: 钟华华		
.XX ± 0.20	DR: 李春风	TITLE: HDMI卡	
.XXX ±		PART NO: HX HDMI 19PIN	
X° ± 1°		SHEET:10F1	
.X° ± 0.5°		REV: A	
UNITS: mm		SCALE: 1:1	



深圳市韩下电子有限公司
Shenzhen Hanxia Electronic Co., Ltd
Tel: 0755-23086569

承 认 书

SPECIFICATION FOR APPROVAL

产 品 编 码
Material code:

产品名称 Project:

HDMI 座

规格型号 Part No:

HX HDMI 19PIN

贵公司承认印 Approval signatures

料 号/Part No.	签 章/Signatures

日期 Date:

拟制/Drawn	黄彬	
审核/Check	张伟	
批准/Approved	罗小春	



1.SCOPE (适用范围)

This product specification defines the product performance and the test methods to ascertain the performance of the HDMI.

本产品规格书规定设计生产的 HDMI 连接器产品的特性及测试方法

2. PRODUCT NAME AND PART NUMBER (产品名称及编号)

Product Name (品名)	Part Number (零件号)
Assembly (产品主体)	
Embossed Package (包装)	

3. RATINGS (额定值)

Ltem（项目）	Standard（标准）	
Rated Voltage(MAX.) （额定电压）	40 V	〔AC/DC〕
Rated Current(MAX.) （额定电流）	0.3A	
Ambient temperature Range （工作温度范围）	-20℃~+85℃.	
Storage temperature Range （存储温度范围）	-40℃ ~ +85℃	
Ambient humidity Range （湿度范围）	95%R.H.MAX	

4. FEATURE & DIMENSIONS (特征及尺寸)

4.1 PRODUCT DIMENSION 产品尺寸

These connectors shall have the dimensions as shown in customer drawing.

本产品的相关尺寸参见客户图面。

4.2 PCB/PANEL LAYOUT (印刷电路板布局)

The recommended PCB layout is shown in customer drawing.

本产品适用的 PCB layout 参见客户图面。

4.3 MATERIAL (材料)

The harmful material can follow the requirement of ROHS.

本产品使用的材料符合 RoHS 指令要求。

4.4 PACKAGING (包装)

Products shall be packaged according to requirements specified in purchase order for safe delivery.

products required tray or carrier tape should meet the proper specification per purchase order. Connector container and the packaging specification is shown in customer drawing.

产品包装可依客户指定要求。本产品采用塑料盘装（卷带包装），具体规格见客户图面。

4.5 MARKING (标识)

Manufacturer's name industry recognized logo or customer approved marks.

标示制造商的名称，或客户认可的相关标志。



4.6 TRANSPORTATION (运输)

Any vehicle can be adopted for the transportation, but moisture-proof and no mechanical damage.

可采用任何运输工具运输，勿淋湿及机械性损伤。

4.7 STORAGE (存贮)

Temperature: $-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$, Relative humidity: $\leq 95\%$, Not to storage in corrosive environments. Are-qualification test shall be conducted immediately while the storage duration exceed 6 months.

温度: $-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$, 相对湿度: $\leq 95\%$; 勿贮存于腐蚀环境内。贮存期超过 6 个月后需重新进行品质确认。

5. PERFORMANCE (性能)

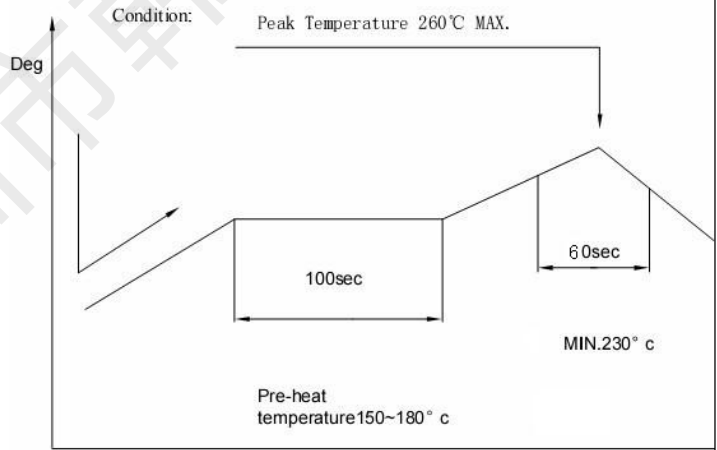
5.1 Electrical (电气性要求)

ITEM (条款)	DESCRIPTION (测试项目)	TEST CONDITIN (测试条件)	REQUIREMENT (必要条件)
5.1.1	Dielectric Withstanding Voltage Resistance 介质耐电压测试	Condition: EIA-364-20, 150V AC for, 1 minute. Test between adjacent contact of unmated samples. 条件: EIA-364-20, 以 150 伏特测试连接器相邻端子一分钟	Requirement: No creeping discharge or flashes occur. Current leakage 1mA Max. 要求: 漏电流最大不超过 1mA.
5.1.2	Contact Resistance 接触阻抗测试	Condition: EIA-364-23, except 100mA maximum test current and 20mV maximum open circuit voltage. 条件: EIA-364-23, 以最大 100mA 电流, 最大 20mV 电压环路测试产品.	Requirement: 30m Ω Max. 要求: 阻抗小于 30 毫欧
5.1.3	Isolation Resistance 绝缘阻抗	Condition: EIA-364-21, method C, 150V DC 条件: EIA-364-21, 方式 C, 电压为 150V 直流	Requirement: 10M Ω Min., final 10M Ω Max., initial 要求: 最小绝缘阻抗大于 100 M 欧
5.1.4	Transmission speed 传输速度	3 to 1 on the channel is a clock, and is TMDS channel (minimize transmission differential signal), and their transmission speeds were 3.4 GBPS 1 对通道是时钟通道, 另外 3 对是 TMDS 通道 (最小化传输差分信号), 他们的传输速度分别为 3.4GBPS	3*3.4=10.2GPBS

5.2 Mechanical (机械性能)

ITEM (条款)	DESCRIPTION (测试项目)	TEST CONDITIN (测试条件)	REQUIREMENT (必要条件)
5.2.1	Durability Cycling 插拔寿命测试	Condition: EIA-364-09, 10000 cycles time, mate and unmated connectors for 100 cycles per hour. 条件: EIA-364-09,在每小时 100 次插拔数次可循环工作 10000 次以上	Requirement: Automatic equipment: 100 $\pm$ 50. 要求: 自动测试机: 100 $\pm$ 50 次/小时
5.2.2	Total Pulling and Insertion Force 产品总插拔力	Condition: EIA-364-13, at a rate of 25 $\pm$ 3mm/minute 条件: EIA-364-13,测试速度为 25 $\pm$ 3mm/分钟	Requirement: Total Pulling Force: 4kgf Max 1.0kgf Min Total Insertion Force: 4.5kgf Max 要求: 总拔出力: 最大 4kgf 最小 1.0 kgf. 总插入力: 最大 4.5kgf
5.2.3	Terminal retention force 端子保持力	Apply axial pull out force at the rate of 25 $\pm$ 3 mm/minute on the terminal assembled in the housing 端子与 Housing 组装后,以操作速度每分钟位移 25 $\pm$ 3MM, 将端子拔出 Housing,进行端子保持力测试	0.3kgf(3N)以上(per pin) 0.3kgf(3N)min 每 PIN 保持力在 0.3kgf 以上.

5.3 ENVIRONMENTAL (环境要求)

ITEM (条款)	DESCRIPTION (测试项目)	TEST CONDITIN (测试条件)	REQUIREMENT (必要条件)
5.3.1	Solderability 焊锡性能	Condition: EIA-364-52. Dip solder tails into the molten solder (held at $230 \pm 5^{\circ}\text{C}$) up to 0.5mm from the tip of tails for $3 \pm 0.5\text{sec}$. 条件: EIA-364-52.将产品的锡镀部分浸入 $230 \pm 5^{\circ}\text{C}$ 的锡炉里, 深度 0.5mm, 时间为 3 ± 0.5 秒.	Requirement: Solder coverage 95% Min. 要求: 需 95%以上区域上锡方可.
5.3.2	Salt Spray 盐雾测试	Condition: MIL-STD-1344, Concentration $5 \pm 1\%$. Ambient temperature $35 \pm 5^{\circ}\text{C}$. Tin feet Spray time 8 hours. Gold-plated area Spray time 12 hours. 条件: MIL-STD-1344,将产品放置于 $5 \pm 1\%$ 的盐雾测试机中., 环境温度要求在 $35 \pm 5^{\circ}\text{C}$, 锡脚盐雾测试 8 小时, 接触点镀金盐雾为 12 小时,	Requirement: No physical damage. Contact Resistance: 100 milliohms Max. 要求: 无生锈现象, 端子接触阻抗不超过 100 毫欧。
5.3.3	Resistance to soldering heat 抗高温焊接性能	Condition: Touch the terminal with the soldering iron (held at $350 \pm 10^{\circ}\text{C}$) for $3 \pm 1\text{seconds}$. However, without too much pressure to the terminal. 条件: 用 $350 \pm 10^{\circ}\text{C}$ 的烙铁接触端子 2-4 秒, 不可用较大压力压端子	Requirement: No appearance damaged. 要求: 无外观不良
5.3.4	Drop 掉落实验	Condition: From 1.5m 条件: 将产品从 1.5m 空中自由落下	Requirement: No physical damage. 要求: 无物理损伤
5.3.5	RESISTANCE TO IR REFLOW 回流焊测试如图	Condition: Peak Temperature 260°C MAX.  Pre-heat temperature $150 \sim 180^{\circ}\text{C}$ MIN. 230°C Temperature condition graph (Temperature on board pattern side)	Requirement: No Damage after 2 times of reflow 要求: 经过两次回流焊, 产品无损伤